

Appl No. 10/803,192
Amdt dated August 8, 2006
Reply to Office Action of May 17, 2006

Atty. Ref. 81754.0111
Customer No. 26021

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

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1-3. (Canceled)

4. (Currently amended) A semiconductor device comprising:

a semiconductor chip having an integrated circuit and electrical interconnections electrically connected to the integrated circuit, the semiconductor chip including bonding pads formed on a surface of the semiconductor chip, each of the bonding pads being part of a corresponding electrical interconnection;

a first resin layer disposed on the semiconductor chip and having ridged edges;

wirings, each being disposed over and electrically connected to a corresponding bonding pad and extending integrally over the first resin layer and over a corresponding ridged edge of the first resin layer and being electrically connected to the corresponding bonding pad; and

external connection terminals, each being disposed on a corresponding wiring and being electrically connected to the corresponding wiring, and a part of each external connection terminal being disposed above and in vertical alignment with the corresponding ridged edge that the corresponding wiring extends over.

5-6. (Canceled)

7. (Original) A circuit board on which the semiconductor device according to claim 4 is mounted.

8. (Original) An electronic apparatus including the semiconductor device according to claim 4.

9-13. (Canceled)

14-15. (Canceled)

16. (Currently amended) A circuit board on which the semiconductor device according to claim 6 4 is mounted.

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17. (Canceled)

18. (Currently amended) An electronic apparatus including the
semiconductor device according to claim ~~6~~ 4.

19-20. (Canceled)